PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3860130

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HENKEL CORPORATION	11/06/2014

RECEIVING PARTY DATA

Name:	HENKEL US IP LLC
Street Address:	ONE HENKEL WAY
City:	ROCKY HILL
State/Country:	CONNECTICUT
Postal Code:	06067

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14273183

CORRESPONDENCE DATA

Fax Number: (860)571-5028

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (908)243-2874
Email: PATENTS.MAILBOX@HENKEL.COM
Correspondent Name: HENKEL CORPORATION
Address Line 1: ONE HENKEL WAY
Address Line 4: ROCKY HILL, CONNECTICUT 06067

ATTORNEY DOCKET NUMBER:	N-3357.CRG.US-DIV
NAME OF SUBMITTER:	JOANNE GUTIERREZ
SIGNATURE:	/JOANNE GUTIERREZ/
DATE SIGNED:	05/05/2016

Total Attachments: 33
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CONFIRMATORY ASSIGNMENT – UNITED STATES OF AMERICA/I

WHEREAS,

HENKEL CORPORATION of One Henkel Way, Rocky Hill, CT, 06067, United States of America; (the "Assignor"),

was the owner of inventions in the United States of America set forth and described in Schedule I attached hereto and forming a part of this document (the "Inventions")

AND WHEREAS,

HENKEL US IP LLC of One Henkel Way, Rocky Hill, CT 06067, United States of America; (the "Assignee"),

had as of October 1, 2013 (the "Effective Date") acquired the entire right, title, interest, property and benefit in and for the United States of America, in and to the Inventions held by the Assignor;

NOW THEREFORE, for good and valuable consideration already provided, the receipt and sufficiency of which are hereby acknowledged,

the Assignor confirms by these presents that the Assignor had, as of the Effective Date, assigned, transferred and set over to the Assignee, and to the Assignee's successors, assigns, nominees or other legal representatives, its entire right, title, interest, property and benefit including any right to sue for past infringements in and for the United States of America, in and to the Inventions, any and all applications filed therefor, including any and all corresponding applications whether in the form of divisions, continuations, re-examinations, re-issues and extensions thereof, any and all patents that may issue, be granted or result therefrom for the Inventions, and any and all rights of priority resulting from the filing of any of the above-identified applications and any previously filed applications in respect of the Inventions under international conventions, treaties or otherwise, the same to be held and enjoyed as fully and exclusively as the same would have been held and enjoyed by the Assignor had this assignment not been made;

the Assignor agrees to do all lawful acts and to execute and deliver, without further consideration, all further documents as may reasonably be required by the Assignee, or by its successors, assigns, nominees, or other legal representatives, to obtain said patents in the United States of America for the Inventions and vests or secures the same in the Assignee, and in the Assignee's successors, assigns, nominees or other legal representatives; and

the Assignor grants to said Assignee, its successors, assigns, nominees or other legal representatives, agents, the power to insert on this Confirmatory Assignment any further information which may be necessary or desirable in order to legally record this document.

THIS CONFIRMATORY ASSIGNMENT may be executed in counterparts, all of which shall be considered one and the same agreement, and is binding on the heirs, executors, successors and administrators of the Assignor.

HENKEL CORPORATION

By ____________________
Name: Steven C. Bauman
Title: Senior Patent Counsel

Date: November 6, 2014

Subscribed and sworn
before me this 6th day
of November, 2014

____
Notary Public

PATRICIA D. RUSSO
NOTARY PUBLIC
MY COMMISSION EXPIRES NOV. 30, 2014

HENKEL US IP LLC

By ____________________
Name: Steven C. Bauman
Title: Senior Patent Counsel

Date: November 6, 2014

Subscribed and sworn
before me this 6th day
of November, 2014

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Notary Public

PATRICIA D. RUSSO
NOTARY PUBLIC
MY COMMISSION EXPIRES NOV. 30, 2014

	A	B	D	E	F	G	H	M
1291	PT026750	N-1598	GB	22 Aug 1996	96 113 481.4	31 May 2000	0761795	HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS
1292	PT026750	N-1598	IT	22 Aug 1996	96 113 481.4	31 May 2000	0761795	HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS
1293	PT026750	N-1598	SE	22 Aug 1996	96 113 481.4	31 May 2000	0761795	HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS
1294	PT026750	N-1598	US	23 May 1996	08/652072	12 May 1998	5750605	HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS
1295	PT026751	N-1600	CA	02 Aug 1996	2182713	02 Jul 2002	2182713	HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY
1296	PT026751	N-1600	DE	06 Aug 1996	96112676.0	31 Mar 1999	69601905.1-08	HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY
1297	PT026751	N-1600	FR	06 Aug 1996	96 112 676.0	31 Mar 1999	0758009	HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY
1298	PT026751	N-1600	IT	06 Aug 1996	96 112 676.0	31 Mar 1999	0758009	HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY
1299	PT026751	N-1600	SE	06 Aug 1996	96 112 676.0	31 Mar 1999	0758009	HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY
1300	PT026751	N-1600	US	08 Aug 1995	08/512579	24 Sep 1996	5559165	HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY
1301	PT026752	N-1603	US	26 Aug 1997	08/918879	22 Dec 1998	5852117	
1302	PT026758	N-1614	US	25 Aug 1997	08/918173	29 Jun 1999	5916968	ADHESIVES RESISTANT TO SKIN-PENETRATING ENHANCERS

	A	B	D	E	F	G	H	M
1303	PT026759	N-1617	US	12 Apr 1996	08/631390	11 Nov 1997	5685758	HOT MELT ADHESIVE COMPOSITIONS WITH IMPROVED WICKING PROPERTIES
1304	PT026760	N-1618	US	12 Apr 1996	08/631388	03 Mar 1998	5723636	METHYLTRIOXORHENIUM-UREA HYDROGEN PEROXIDE EPOXIDATION OF OLEFINS
1305	PT026763	N-1623	US	09 Apr 1996	08/629851	03 Mar 1998	5723222	
1306	PT026764	N-1625	US	06 May 1996	08/643644	18 Aug 1998	5795397	CHEMICALLY DERIVATIZED MALTODEXTRINS
1307	PT026765	N-1626	US	06 May 1996	08/643643	18 Nov 1997	5688845	HIGH SOLIDS, MALTODEXTRIN-BASED ADHESIVES
1308	PT026765	N-1626	US	30 Apr 1997	08/841555	03 Aug 1999	5932639	HIGH SOLIDS, MALTODEXTRIN-BASED ADHESIVES
1309	PT026767	N-1633	US	05 Aug 1996	08/693920	19 May 1998	5753468	STABLE HIGH-VISCOSITY STARCH BASED ADHESIVE AND METHOD OF PREPARATION
1310	PT026770	N-1640	US	27 Sep 1996	08/722786	10 Feb 1998	5716441	STARCH-BASED, WATER RESISTANT ADHESIVES
1311	PT026771	N-1642	EP	21 Jul 1997	97112455.7	20 Jun 2001	0832906	WATER RESISTANT, VISCOSITY STABLE, ALKALINE CORRUGATING ADHESIVE COMPOSITION
1312	PT026771	N-1642	US	18 Dec 1998	09/215821	03 Jul 2001	6255369	WATER RESISTANT, VISCOSITY STABLE, ALKALINE CORRUGATING ADHESIVE COMPOSITION
1313	PT026771	N-1642	US	27 Feb 2001	09/802533	23 Apr 2002	6375775	WATER RESISTANT, VISCOSITY STABLE, ALKALINE CORRUGATING ADHESIVE COMPOSITION
1314	PT026775	N-1666	BE	14 Oct 1997	97 911 739.7	24 Jul 2002	0935616	ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURINGSAME
1315	PT026775	N-1666	CH	14 Oct 1997	97 911 739.7	24 Jul 2002	0935616	ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURINGSAME
1316	PT026775	N-1666	DE	31 Oct 1996	19643959.0			ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURINGSAME
1317	PT026775	N-1666	DE	14 Oct 1997	97911739.7	24 Jul 2002	69714280.9-08	ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURINGSAME

	A	B	D	E	F	G	H	M
1325	PT026775	N-1666	TR	14 Oct 1997	99/930	21 May 2009	TR 1999 00930 B	ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURINGSAME
1326	PT026775	N-1666	US	12 Sep 1997	08/928313	23 Nov 1999	5990229	ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURINGSAME
1327	PT026776	N-1669	JP	15 May 1998	0			REACTIVE RADIATION- OR THERMALLY-INITIATED CATIONICALLY- CURABLE EPOXIDE MONOMERSAND COMPOSITIONS MADE FROM THOSE MONOME
1328	PT026776	N-1669	US	14 May 1998	09/078768	05 Oct 1999	5962547	REACTIVE RADIATION- OR THERMALLY-INITIATED CATIONICALLY- CURABLE EPOXIDE MONOMERSAND COMPOSITIONS MADE FROM THOSE MONOME
1329	PT026778	N-1674	MX	01 Jul 1998	985377	28 Jul 2011	288800	ABSORBENT ARTICLES COMPRISING A POLYETHER-CONTAINING HOT MELT ADHESIVE AND HOTMELT ADHESIVE COMPOSITIONS COMPRISING POLY
1330	PT026778	N-1674	TW	01 Jul 1998	87110675			ABSORBENT ARTICLES COMPRISING A POLYETHER-CONTAINING HOT MELT ADHESIVE AND HOTMELT ADHESIVE COMPOSITIONS COMPRISING POLY
1331	PT026779	N-1675	US	28 Jul 1997	08/901305	22 Dec 1998	5852080	HOT MELT ADHESIVES WITH COMPATIBLE HYDROXYL-CONTAINING ESTER WAXES
1332	~~PT026782~~	~~N-1683~~	~~US~~	~~26 Aug 1997~~	~~08/918795~~	~~23 Mar 1999~~	~~5886071~~	~~STABLE HIGH PERFORMANCE, ONE-PART ACRYLIC~~ ADHESIVE SYSTEM☐
1333	~~PT026784~~	~~N-1688~~	~~US~~	~~02 Jun 1995~~	~~08/460357~~			~~THE SYNTHESIS OF CONDENSATION POLYMERS IN~~ DENSIFIED FLUIDS
1334	PT026784	N-1688	US	14 Feb 1997	08/800371	16 Jan 2001	6174956	THE SYNTHESIS OF CONDENSATION POLYMERS IN DENSIFIED FLUIDS
1335	PT026785	N-1690	DE	12 Oct 1998	EP19980119240.4	15 Mar 2006	69833823.5-08	FAST SETTING POLYURETHANE HOT MELT ADHESIVE
1336	PT026785	N-1690	JP	14 Oct 1998	10-292104			FAST SETTING POLYURETHANE HOT MELT ADHESIVE

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1337	PT026785	N-1690	US	15 Oct 1997	08/951055	17 Aug 1999	5939488	FAST SETTING POLYURETHANE HOT MELT ADHESIVE
1338	PT026787	N-1693	DE	22 Oct 1998	98120011.6	10 Oct 2007	69838537	ENHANCER-RESISTANT PRESSURE SENSITIVE ADHESIVE COMPOSITION FOR TRANSDERMALDRUG DELIVERY
1339	PT026787	N-1693	GB	22 Oct 1998	98120011.6	10 Oct 2007	0913445	ENHANCER-RESISTANT PRESSURE SENSITIVE ADHESIVE COMPOSITION FOR TRANSDERMALDRUG DELIVERY
1340	PT026787	N-1693	IT	22 Oct 1998	98120011.6	10 Oct 2007	0913445	ENHANCER-RESISTANT PRESSURE SENSITIVE ADHESIVE COMPOSITION FOR TRANSDERMALDRUG DELIVERY
1341	PT026787	N-1693	JP	27 Oct 1998	10-305122	14 Jan 2011	4660830	ENHANCER-RESISTANT PRESSURE SENSITIVE ADHESIVE COMPOSITION FOR TRANSDERMALDRUG DELIVERY
1342	PT026787	N-1693	US	28 Oct 1997	08/958862	20 Jun 2000	6077527	ENHANCER-RESISTANT PRESSURE SENSITIVE ADHESIVE COMPOSITION FOR TRANSDERMALDRUG DELIVERY
1343	PT026789	N-1695	US	21 Jan 1998	09/010082	15 Aug 2000	6103388	USE OF LOW TOXICITY SOLVENTS IN WATERBORNE ADHESIVES
1344	PT026790	N-1698	CA	04 Feb 1999	2260675	06 Apr 2010	2260675	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1345	PT026790	N-1698	DE	02 Feb 1999	99101564.5	26 Sep 2007	69937164.3	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1346	PT026790	N-1698	ES	02 Feb 1999	99101564.5	26 Sep 2007	0934990	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1347	PT026790	N-1698	FR	02 Feb 1999	99101564.5	26 Sep 2007	0934990	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1348	PT026790	N-1698	GB	02 Feb 1999	99101564.5	26 Sep 2007	0934990	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE

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1349	PT026790	N-1698	JP	03 Feb 1999	11-025853	15 Jul 2011	4782258	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1350	PT026790	N-1698	MX	03 Feb 1999	991234	20 May 2003	214341	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1351	PT026790	N-1698	US	04 Feb 1998	09/018634	12 Sep 2000	6117945	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1352	PT026791	N-1699	US	12 Nov 1998	09/190156	13 Mar 2001	6201099	
1353	PT026794	N-1710	JP	22 Jan 1999	11-014250	14 Jan 2011	4660699	ADHESIVE COMPOSITION WITH SMALL PARTICLE SIZE FOR MICROELECTRONIC DEVICES
1354	PT026794	N-1710	KR	22 Jan 1999	99-1962	24 Mar 2006	10-0566551	ADHESIVE COMPOSITION WITH SMALL PARTICLE SIZE FOR MICROELECTRONIC DEVICES
1355	PT026794	N-1710	US	23 Jan 1998	09/012354	08 Feb 2000	6022616	ADHESIVE COMPOSITION WITH SMALL PARTICLE SIZE FOR MICROELECTRONIC DEVICES
1356	PT026807	N-1731	CN	30 Jun 1999	99110932.5	02 Nov 2005	99110932.5	METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS
1357	PT026807	N-1731	DE	01 Jul 1999	99112733.3	11 Oct 2006	69933512.4-08	METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS
1358	PT026807	N-1731	FI	01 Jul 1999	99112733.3	11 Oct 2006	0969064	METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS
1359	PT026807	N-1731	FR	01 Jul 1999	99112733.3	11 Oct 2006	0969064	METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS
1360	PT026807	N-1731	IT	01 Jul 1999	99112733.3	11 Oct 2006	0969064	METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS
1361	PT026807	N-1731	KR	01 Jul 1999	99-26328	21 Sep 2005	10-0517454	METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS

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1362	PT026807	N-1731	US	02 Jul 1998	09/110080	02 May 2000	6057381	METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS
1363	PT026807	N-1731	US	22 Dec 1999	09/469479	30 Jan 2001	6180187	METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS
1364	PT026810	N-1734	CN	30 Jun 1999	99111395.0	14 Apr 2004	99111395.0	DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES
1365	PT026810	N-1734	CN	10 Apr 2001	01119283.6	19 Apr 2006	01119283.6	DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES
1366	PT026810	N-1734	DE	01 Jul 1999	99112734.1	06 Oct 2004	69920813	DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES
1367	PT026810	N-1734	FR	01 Jul 1999	99112734.1	06 Oct 2004	0969065	DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES
1368	PT026810	N-1734	IT	01 Jul 1999	99112734.1	06 Oct 2004	0969065	DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES
1369	PT026810	N-1734	KR	02 Jul 1999	99-26638	12 Jul 2006	10-0602887	DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES
1370	PT026810	N-1734	KR	10 Apr 2001	10-2001-0019038	17 Jan 2008	10-0795423	DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES
1371	PT026810	N-1734	NL	01 Jul 1999	99112734.1	06 Oct 2004	0969065	DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES
1372	PT026810	N-1734	TW	01 Jul 1999	88111220	24 Dec 2002	162346	DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES
1373	~~PT026810~~	~~N-1734~~	~~US~~	~~02 Jul 1998~~	~~60/091492~~			~~DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC~~ DEVICES

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1374	PT026810	N-1734	US	14 Apr 2000	09/549639	12 Mar 2002	6355750	DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES
1375	PT026811	N-1735	US	02 Jul 1998	09/110047	16 May 2000	6063828	Underfulle Encapsulant Compositions For Use In Electronic Devices
1376	PT026812	N-1736	CN	30 Jun 1999	99119202.8	03 Mar 2004	99119202.8	PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES
1377	PT026812	N-1736	CN	14 Aug 2000	200310124361.9	19 Jul 2006	200310124361.9	PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES
1378	PT026812	N-1736	DE	01 Jul 1999	99112725.9	11 Apr 2007	69935758.6-08	PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES
1379	PT026812	N-1736	FR	01 Jul 1999	99112725.9	11 Apr 2007	0969063	PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES
1380	PT026812	N-1736	IT	01 Jul 1999	99112725.9	11 Apr 2007	0969063	PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES
1381	PT026812	N-1736	JP	02 Jul 1999	189376/99	19 Apr 2002	3299522	PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES
1382	PT026812	N-1736	NL	01 Jul 1999	99112725.9	11 Apr 2007	0969063	PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES
1383	PT026812	N-1736	TW	01 Jul 1999	88111221	10 Sep 2002	NI-155712	PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES
1384	~~PT026812~~	~~N-1736~~	~~US~~	~~02 Jul 1998~~	~~60/091493~~			~~PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN~~ ELECTRONIC DEVICES
1385	PT026812	N-1736	US	18 Jun 1999	09/336246	13 Nov 2001	6316566	PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES

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1386	PT026812	N-1736	US	28 Jun 2001	09/894540	26 Feb 2002	6350838	PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES
1387	PT026816	N-1749	EP	14 Jul 2000	00948685.3	11 Mar 2009	1301565	REAGENTS FOR HEAT ACTIVATED POLYMER CROSSLINKING
1388	~~PT026822~~	~~N-1771~~	~~US~~	~~04 Nov 1998~~	~~09/186237~~			
1389	PT026825	N-1786	DE	05 Apr 2000	00107108.3	08 Dec 2004	60016493.4-08	USE OF ANIONIC OR CATIONIC PLASTICIZERS WITH SULFONATED POLYESTERS IN HOTMELT FORMULATIONS
1390	PT026825	N-1786	FR	05 Apr 2000	00107108.3	08 Dec 2004	1043376	USE OF ANIONIC OR CATIONIC PLASTICIZERS WITH SULFONATED POLYESTERS IN HOTMELT FORMULATIONS
1391	PT026825	N-1786	GB	05 Apr 2000	00107108.3	08 Dec 2004	1043376	USE OF ANIONIC OR CATIONIC PLASTICIZERS WITH SULFONATED POLYESTERS IN HOTMELT FORMULATIONS
1392	PT026825	N-1786	JP	07 Apr 2000	2000-111920	05 Nov 2010	4620213	USE OF ANIONIC OR CATIONIC PLASTICIZERS WITH SULFONATED POLYESTERS IN HOTMELT FORMULATIONS
1393	PT026825	N-1786	US	09 Apr 1999	09/289451	14 Dec 1999	6001910	USE OF ANIONIC OR CATIONIC PLASTICIZERS WITH SULFONATED POLYESTERS IN HOTMELT FORMULATIONS
1394	PT026826	N-1791	CN	23 Dec 1999	99122973.8	18 Oct 2006	99122973.8	MULTIPURPOSE HOT MELT ADHESIVE
1395	PT026826	N-1791	DE	22 Dec 1999	99125904.5	25 Feb 2009	69940460.6-08	MULTIPURPOSE HOT MELT ADHESIVE
1396	PT026826	N-1791	GB	22 Dec 1999	99 125 904.5	25 Feb 2009	1013733	MULTIPURPOSE HOT MELT ADHESIVE

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1397	PT026826	N-1791	IT	22 Dec 1999	99 125 904.5	25 Feb 2009	1013733	MULTIPURPOSE HOT MELT ADHESIVE
1398	PT026826	N-1791	JP	22 Dec 1999	11-363997	03 Aug 2012	5053474	MULTIPURPOSE HOT MELT ADHESIVE
1399	PT026826	N-1791	KR	23 Dec 1999	99-60911	16 Mar 2009	10-0889998	MULTIPURPOSE HOT MELT ADHESIVE
1400	PT026826	N-1791	MX	17 Dec 1999	9912107	22 Mar 2004	219488	MULTIPURPOSE HOT MELT ADHESIVE
1401	PT026826	N-1791	SE	22 Dec 1999	99 125 904.5	25 Feb 2009	1013733	MULTIPURPOSE HOT MELT ADHESIVE
1402	PT026826	N-1791	TW	21 Dec 1999	88122598			MULTIPURPOSE HOT MELT ADHESIVE
1403	PT026826	N-1791	US	23 Dec 1998	09/219938	15 May 2001	6232391	MULTIPURPOSE HOT MELT ADHESIVE
1404	PT026826	N-1791	US	13 Apr 2000	09/548545	21 May 2002	6391960	MULTIPURPOSE HOT MELT ADHESIVE
1405	PT026829	N-1797	CH	23 Jun 2000	10154218.1	24 Jul 2013	2183986	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE FOR CIGARETTEPREPARATION
1406	PT026829	N-1797	DE	23 Jun 2000	10154218.1	24 Jul 2013	60048155.7	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE FOR CIGARETTEPREPARATION
1407	PT026829	N-1797	DE					LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE FOR CIGARETTEPREPARATION
1408	PT026829	N-1797	EP	23 Jun 2000	10154218.1	24 Jul 2013	2183986	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE FOR CIGARETTEPREPARATION

	A	B	D	E	F	G	H	M
1419	PT026829	N-1797	SE	23 Jun 2000	10154218.1	24 Jul 2013	2183986	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE FOR CIGARETTEPREPARATION
1420	PT026829	N-1797	US	26 Apr 1999	09/299516	27 May 2003	6568399	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE FOR CIGARETTEPREPARATION
1421	PT026830	N-1803	US	09 Mar 1999	09/264999	26 Dec 2000	6165613	Adhesive Paste for Semiconductors
1422	PT026831	N-1805	US	13 Feb 2001	09/782421	05 Feb 2002	6344157	CONDUCTIVE AND RESISTIVE MATERIALS WITH ELECTICAL STABILITYFOR USE IN ELECTRONICSDEVICES
1423	PT026832	N-1806	JP	07 Apr 2000	2000-111922	17 Dec 2010	4644769	HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS COMPRISING WETNESS INDICATOR
1424	PT026832	N-1806	MX	07 Apr 2000	3454	28 Jan 2008	253915	HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS COMPRISING WETNESS INDICATOR
1425	PT026833	N-1807	JP	07 Apr 2000	2000-111923	17 Dec 2010	4644770	USE OF HIGH HYDROXYL COMPOUNDS FOR WATER SENSITIVE HOT MELTADHESIVES
1426	PT026833	N-1807	US	09 Apr 1999	09/289025	25 Jun 2002	6410627	USE OF HIGH HYDROXYL COMPOUNDS FOR WATER SENSITIVE HOT MELTADHESIVES
1427	PT026838	N-1824	CN	16 May 2001	01119711.0	11 Jan 2006	01119711.0	CURABLE ELECTRON DONOR COMPOUNDS
1428	PT026838	N-1824	EP	16 May 2001	01111274.5			CURABLE ELECTRON DONOR COMPOUNDS
1429	PT026838	N-1824	JP	16 May 2001	2001-146658	14 Nov 2008	P4216489	CURABLE ELECTRON DONOR COMPOUNDS
1430	PT026838	N-1824	JP	05 Sep 2008	2008-228932	25 Nov 2011	4870738	CURABLE ELECTRON DONOR COMPOUNDS
1431	PT026838	N-1824	KR	16 May 2001	2001-0026768	08 Jan 2008	10-0794633	CURABLE ELECTRON DONOR COMPOUNDS

	A	B	D	E	F	G	H	M
1432	PT026840	N-1827	JP	07 Jun 2000	2001-502528	07 Sep 2012	5079957	HOT MELT PRESSURE SENSITIVE ADHESIVE BASED ON COMPATIBILIZED BLENDS OF ELASTOMERS
1433	PT026840	N-1827	US	07 Jun 1999	09/326856	19 Dec 2000	6162859	HOT MELT PRESSURE SENSITIVE ADHESIVE BASED ON COMPATIBILIZED BLENDS OF ELASTOMERS
1434	PT026842	N-1829	CN	07 Jul 1999	99110951.1	06 Oct 2004	99110951.1	EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS
1435	PT026842	N-1829	DE	07 Jul 1999	99113152.5	17 Sep 2003	69911320.2	EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS
1436	PT026842	N-1829	GB	07 Jul 1999	99113152.5	17 Sep 2003	971009	EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS
1437	PT026842	N-1829	JP	07 Jul 1999	1999-193327	20 Nov 2009	4408484	EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS
1438	PT026842	N-1829	SG	07 Jul 1999	9903317-7	31 Aug 2006	74150	EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS
1439	PT026842	N-1829	US	06 Jul 1999	09/347794	01 May 2001	6225379	EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS
1440	PT026843	N-1839	US	14 Oct 1999	09/417347			
1441	PT026845	N-1843	DE	31 Oct 2000	00123391.5	09 Feb 2005	60018015.8-08	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1442	PT026845	N-1843	FR	31 Oct 2000	001233915	09 Feb 2005	1099742	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE

	A	B	D	E	F	G	H	M
1443	PT026845	N-1843	GB	31 Oct 2000	001233915	09 Feb 2005	1099742	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1444	PT026845	N-1843	IT	31 Oct 2000	001233915	09 Feb 2005	1099742	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1445	PT026845	N-1843	SE	31 Oct 2000	001233915	09 Feb 2005	1099742	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1446	PT026845	N-1843	US	12 Nov 1999	09/439655	28 Mar 2006	7019060	LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
1447	PT026849	N-1852	US	18 May 2000	09/573838	09 Oct 2001	6300456	COMPOUNDS WITH ELECTRON DONOR AND ELECTRON ACCEPTOR FUNCTIONALITY
1448	PT026850	N-1853.TDM	CH	08 Feb 2001	01909120.6	15 Apr 2009	1257258	BIOADHESIVE COMPOSITION
1449	PT026850	N-1853.TDM	DE	08 Feb 2001	01909120.6	15 Apr 2009	1257258	BIOADHESIVE COMPOSITION
1450	PT026850	N-1853.TDM	FR	08 Feb 2001	01909120.6	15 Apr 2009	1257258	BIOADHESIVE COMPOSITION
1451	PT026850	N-1853.TDM	GB	08 Feb 2001	01909120.6	15 Apr 2009	1257258	BIOADHESIVE COMPOSITION
1452	PT026850	N-1853.TDM	US	11 Feb 2000	09/502585	04 Sep 2001	6284235	BIOADHESIVE COMPOSITION
1453	PT026851	N-1858	US	29 Feb 2000	09/515881	18 Nov 2003	6649259	ADHESIVES FOR THERMALLY SHRINKABLE FILMS OR LABELS

	A	B	D	E	F	G	H	M
1454	PT026852	N-1859	US	02 Mar 2000	09/517412	26 Nov 2002	6486229	
1455	PT026853	N-1860	JP	05 Apr 2001	2001-575103	04 Nov 2011	4854161	WATER BASED ADHESIVE COMPOSITION WITH RELEASE PROPERTIES
1456	PT026853	N-1860	US	05 Apr 2000	09/543692	14 May 2002	6387475	WATER BASED ADHESIVE COMPOSITION WITH RELEASE PROPERTIES
1457	PT026854	N-1861	CN	16 May 2001	01119710.2	15 Dec 2004	01119710.2	DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY
1458	PT026854	N-1861	DE	16 May 2001	01111271.1	16 Mar 2005	60109356.9-08	DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY
1459	PT026854	N-1861	FR	16 May 2001	01111271.1	16 Mar 2005	1156068	DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY
1460	PT026854	N-1861	IT	16 May 2001	01111271.1	16 Mar 2005	1156068	DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY
1461	PT026854	N-1861	KR	16 May 2001	2001-0026769	20 Dec 2007	10-0789332	DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY
1462	PT026854	N-1861	TW	17 May 2001	90112030	01 Oct 2008	I-301491	DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY
1463	PT026859	N-1869	CN	05 Jul 2001	01122563.7	16 Mar 2005	01122563.7	DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS
1464	PT026859	N-1869	DE	04 Jul 2001	01115670.0	16 Mar 2005	60109366.6-08	DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS
1465	PT026859	N-1869	EP	04 Jul 2001	01115670.0	16 Mar 2005	1170346	DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS

	A	B	D	E	F	G	H	M
1466	PT026859	N-1869	FR	04 Jul 2001	01115670.0	16 Mar 2005	1170346	DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS
1467	PT026859	N-1869	IT	04 Jul 2001	01115670.0	16 Mar 2005	1170346	DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS
1468	PT026859	N-1869	JP	04 Jul 2001	2001-203485	02 Jul 2010	4541599	DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS
1469	PT026859	N-1869	KR	05 Jul 2001	2001-0040099	08 Jan 2008	794636	DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS
1470	PT026859	N-1869	TW	04 Jul 2001	90116527	21 Dec 2004	225513	DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS
1471	PT026859	N-1869	US	07 Jul 2000	09/611899	15 Jun 2004	6750301	DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS
1472	PT026860	N-1870	US	23 Jun 2000	09/603155	28 Aug 2001	6280515	
1473	PT026861	N-1871	US	23 Jun 2000	09/602736	28 Aug 2001	6280514	
1474	PT026862	N-1873	US	21 Apr 2000	09/556721	19 Nov 2002	6482878	POLYURETHANE HOTMELT ADHESIVES WITH ACRYLIC COPOLYMERS AND THERMOPLASTIC RESINS
1475	PT026863	N-1875	BE	19 Jun 2000	00942950.7	18 Sep 2002	1121295	GLUE FOR LABELS
1476	PT026863	N-1875	DE	19 Jun 2000	00942950.7	18 Sep 2002	60000477.5	GLUE FOR LABELS
1477	PT026863	N-1875	ES	19 Jun 2000	00942950.7	18 Sep 2002	1121295	GLUE FOR LABELS

	A	B	D	E	F	G	H	M
1478	PT026863	N-1875	FR	19 Jun 2000	00942950.7	18 Sep 2002	1121295	GLUE FOR LABELS
1479	PT026863	N-1875	GB	19 Jun 2000	00942950.7	18 Sep 2002	1121295	GLUE FOR LABELS
1480	PT026863	N-1875	IT	19 Jun 2000	00942950.7	18 Sep 2002	1121295	GLUE FOR LABELS
1481	PT026863	N-1875	NL	19 Jun 2000	00942950.7	18 Sep 2002	1121295	GLUE FOR LABELS
1482	PT026870	N-1892	US	18 Oct 2000	09/623378	25 Mar 2003	6537359	CONDUCTIVE INK OR PAINT
1483	PT026873	N-1899	US	25 Oct 2000	09/696799	18 Nov 2003	6648955	Corrugating adhesive
1484	PT026881	N-1912	US	29 Dec 2000	09/752260	10 Sep 2002	6448303	HOT MELT ADHESIVES FOR DERMAL APPLICATION
1485	PT026882	N-1913.EEM	US	09 Jan 2001	09/757210	03 Jun 2003	6572790	CATHODE COATING DISPERSION
1486	PT026884	N-1917.ADH	US	06 Feb 2001	09/777281	15 Jul 2003	6593407	HOT MELT ADHESIVE COMPOSITION
1487	PT026885	N-1922.PSA	US	16 Mar 2001	09/809802	04 Nov 2003	6642298	Rubber-acrylic adhesive formulation
1488	PT026886	N-1925.EEM	US	25 Apr 2001	09/841980	24 Jun 2003	6583201	CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY FOR USE IN ELECTRONICS DEVICES
1489	PT026887	N-1927.BKB	US	27 Apr 2001	09/844907	22 Feb 2005	6858695	CURABLE HOT MELT ADHESIVES FOR CASEMAKING
1490	PT026889	N-1930.EEM	US	21 Jun 2001	09/887450	10 Dec 2002	6492437	SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING CATALYSTS
1491	PT026890	N-1932.BDG	US	15 Jun 2001	09/882115	02 Sep 2003	6613836	REACTIVE HOT MELT ADHESIVE

	A	B	D	E	F	G	H	M
1492	PT026892	N-1935.PSA	US	26 Jun 2001	09/891985	12 Oct 2004	6803081	RADIATION CURABLE ADHESIVE
1493	PT026929	N-2023.PKG	CN	06 May 2003	03810316.8			HOT MELT ADHESIVE COMPOSITION
1494	PT027174	N-3248.EM	TW	16 May 2008	97117929			ORGANIC ELECTRONIC DEVICES PROTECTED BY ELASTOMERIC LAMINATING ADHESIVE
1495	PT026382	N-3266.CRG	CA	02 Sep 2009	2737042			Water Resistant Adhesive and Methods of Use
1496	PT026382	N-3266.CRG	US	12 Sep 2008	12/209611	20 Mar 2012	8137792	Water Resistant Adhesive and Methods of Use
1497	PT026366	N-3268.TDM	BR	22 Oct 2009	PI0919869.5			Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor
1498	PT026366	N-3268.TDM	CN	22 Oct 2009	200980142499.7			Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor
1499	PT026366	N-3268.TDM	EP	22 Oct 2009	09744012.7			Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor
1500	PT026366	N-3268.TDM	IN	22 Oct 2009	3361/CHENP/2011			Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor
1501	PT026366	N-3268.TDM	JP	22 Oct 2009	2011-533328			Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor
1502	PT026366	N-3268.TDM	KR	22 Oct 2009	2011-7011716			Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor
1503	PT026366	N-3268.TDM	RU	22 Oct 2009	2011120438			Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor
1504	PT026366	N-3268.TDM	TW	23 Oct 2009	98136057			Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor
1505	PT026366	N-3268.TDM	US	24 Apr 2012	13/454592			Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor
1506	PT027200	N-3284.ADH	EP	09 Feb 2009	09707743.2			HOT MELT ADHESIVE

	A	B	D	E	F	G	H	M
1507	~~PT027208~~	~~N-3293.BDM~~	~~US~~	~~20 Jul 2012~~	~~13/553856~~			~~BULK HOT MELT ADHESIVE PACKAGING~~
1508	PT027209	N-3294.BDM	BR	20 Mar 2009	PI0909448.2			Two Part Hybrid Adhesive
1509	PT027209	N-3294.BDM	CA	20 Mar 2009	2719758			Two Part Hybrid Adhesive
1510	PT027209	N-3294.BDM	CN	20 Mar 2009	200980115869.8			Two Part Hybrid Adhesive
1511	PT027209	N-3294.BDM	EP	20 Mar 2009	09726378.4			Two Part Hybrid Adhesive
1512	PT027209	N-3294.BDM	IN	20 Mar 2009	3601/KOLNP/2010			Two Part Hybrid Adhesive
1513	PT027209	N-3294.BDM	JP	20 Mar 2009	2011-501929			Two Part Hybrid Adhesive
1514	PT027209	N-3294.BDM	KR	20 Mar 2009	10-2010-7024061			Two Part Hybrid Adhesive
1515	PT027209	N-3294.BDM	MX	20 Mar 2009	MX/a/2010/010677			Two Part Hybrid Adhesive
1516	PT027209	N-3294.BDM	US	28 Mar 2008	12/058023			Two Part Hybrid Adhesive
1517	PT027210	N-3295.BDM	BR	26 Mar 2009	PI0910069.5			HIGH HEAT RESISTANT ADHESIVE AND SEALANT COMPOSITIONS
1518	PT027210	N-3295.BDM	CN	26 Mar 2009	200980117875.7			HIGH HEAT RESISTANT ADHESIVE AND SEALANT COMPOSITIONS
1519	PT027210	N-3295.BDM	EP	26 Mar 2009	09728873.2			HIGH HEAT RESISTANT ADHESIVE AND SEALANT COMPOSITIONS
1520	PT027210	N-3295.BDM	JP	26 Mar 2009	2011-503044			HIGH HEAT RESISTANT ADHESIVE AND SEALANT COMPOSITIONS
1521	PT027210	N-3295.BDM	US	01 Apr 2008	12/060553	08 Jan 2013	8349123	HIGH HEAT RESISTANT ADHESIVE AND SEALANT COMPOSITIONS
1522	PT026370	N-3309.PSA	CH	02 Sep 2009	09775392.5	06 Jun 2012	2328990	Acrylic PSA With High Impact Resistance
1523	PT026370	N-3309.PSA	DE	02 Sep 2009	09775392.5	06 Jun 2012	602009007505.5	Acrylic PSA With High Impact Resistance
1524	PT026370	N-3309.PSA	EP	02 Sep 2009	09775392.5	06 Jun 2012	2328990	Acrylic PSA With High Impact Resistance
1525	PT026370	N-3309.PSA	FR	02 Sep 2009	09775392.5	06 Jun 2012	2328990	Acrylic PSA With High Impact Resistance
1526	PT026370	N-3309.PSA	GB	02 Sep 2009	09775392.5	06 Jun 2012	2328990	Acrylic PSA With High Impact Resistance
1527	PT026370	N-3309.PSA	IT	02 Sep 2009	09775392.5	06 Jun 2012	2328990	Acrylic PSA With High Impact Resistance
1528	PT026370	N-3309.PSA	US	16 Sep 2008	12/211500	24 Jan 2012	8101276	Acrylic PSA With High Impact Resistance

	A	B	D	E	F	G	H	M
1529	PT027221	N-3314.EM	CN	02 Jul 2009	200980125635.1			THIXOTROPIC CONDUCTIVE COMPOSITION
1530	PT027221	N-3314.EM	EP	02 Jul 2009	09774486.6			THIXOTROPIC CONDUCTIVE COMPOSITION
1531	PT027221	N-3314.EM	JP	02 Jul 2009	2011-516865			THIXOTROPIC CONDUCTIVE COMPOSITION
1532	PT027221	N-3314.EM	KR	02 Jul 2009	2011-7001603			THIXOTROPIC CONDUCTIVE COMPOSITION
1533	PT027221	N-3314.EM	KR	03 Apr 2013	2013-7008573			THIXOTROPIC CONDUCTIVE COMPOSITION
1534	PT027221	N-3314.EM	TW	01 Jul 2009	98122270			THIXOTROPIC CONDUCTIVE COMPOSITION
1535	PT027463	N-3319.PSA	EP	02 Sep 2009	09792172.0			ACRYLIC PRESSURE SENSITIVE ADHESIVE FORMULATION AND ARTICLES COMPRISING SAME
1536	PT027463	N-3319.PSA	US	16 Sep 2008	12/211481	14 May 2013	8440304	ACRYLIC PRESSURE SENSITIVE ADHESIVE FORMULATION AND ARTICLES COMPRISING SAME
1537	PT027223	N-3320.EM	EP	03 Jul 2008	08773016.4			SILVER COATED FLAKY MATERIAL FILLED CONDUCTIVE CURABLE COMPOSITION AND THEAPPLICATION IN DIE ATTACH
1538	PT027223	N-3320.EM	JP	03 Jul 2008	2011-515055			SILVER COATED FLAKY MATERIAL FILLED CONDUCTIVE CURABLE COMPOSITION AND THEAPPLICATION IN DIE ATTACH
1539	PT027223	N-3320.EM	KR	03 Jul 2008	2011-7001602			SILVER COATED FLAKY MATERIAL FILLED CONDUCTIVE CURABLE COMPOSITION AND THEAPPLICATION IN DIE ATTACH
1540	PT027223	N-3320.EM	KR	25 Jun 2013	2013-7016477			SILVER COATED FLAKY MATERIAL FILLED CONDUCTIVE CURABLE COMPOSITION AND THEAPPLICATION IN DIE ATTACH
1541	PT027223	N-3320.EM	TW	10 Dec 2008	97147927			SILVER COATED FLAKY MATERIAL FILLED CONDUCTIVE CURABLE COMPOSITION AND THEAPPLICATION IN DIE ATTACH
1542	PT027464	N-3322.BDM	BR	10 Dec 2009	P10922194.8			Reactive Hot Melt Adhesive
1543	PT027464	N-3322.BDM	CN	10 Dec 2009	200980149614.3			Reactive Hot Melt Adhesive
1544	PT027464	N-3322.BDM	EP	10 Dec 2009	09832523.6			Reactive Hot Melt Adhesive
1545	PT027464	N-3322.BDM	US	12 Dec 2008	12/333795	02 Oct 2012	8277601	Reactive Hot Melt Adhesive

	A	B	D	E	F	G	H	M
1546	PT027468	N-3327.EM	CN	20 Nov 2009	200980146563.9			Phase Separated Curable Compositions
1547	PT027468	N-3327.EM	EP	20 Nov 2009	09828287.4			Phase Separated Curable Compositions
1548	PT027468	N-3327.EM	JP	20 Nov 2009	2011-537650			Phase Separated Curable Compositions
1549	PT027468	N-3327.EM	KR	20 Nov 2009	2011-7014190			Phase Separated Curable Compositions
1550	PT027468	N-3327.EM	TW	20 Nov 2009	98139531			Phase Separated Curable Compositions
1551	PT027468	N-3327.EM	US	13 May 2011	13/106967	23 Apr 2013	8426986	Phase Separated Curable Compositions
1552	PT027515	N-3328.TDM	BR	23 Apr 2010	PI1014886-8			Silicone Acryolic Hybrid Polymer-Based Adhesives
1553	PT027515	N-3328.TDM	CN	23 Apr 2010	201080028046.4			Silicone Acryolic Hybrid Polymer-Based Adhesives
1554	PT027515	N-3328.TDM	EP	23 Apr 2010	10767829.4			Silicone Acryolic Hybrid Polymer-Based Adhesives
555	PT027515	N-3328.TDM	JP	23 Apr 2010	2012-507419			Silicone Acryolic Hybrid Polymer-Based Adhesives
1556	PT027515	N-3328.TDM	KR	23 Nov 2011	2011-7027981			Silicone Acryolic Hybrid Polymer-Based Adhesives
1557	PT027515	N-3328.TDM	RU	23 Nov 2011	2011147589			Silicone Acryolic Hybrid Polymer-Based Adhesives
1558	PT027515	N-3328.TDM	TW	23 Apr 2010	99112902			Silicone Acryolic Hybrid Polymer-Based Adhesives
1559	PT027515	N-3328.TDM	US	24 Oct 2011	13/279721			Silicone Acryolic Hybrid Polymer-Based Adhesives

	A	B	D	E	F	G	H	M
1560	PT026381	N-3329.CRG	US	08 Jul 2011	13/178799	06 Aug 2013	8501326	Wax Replacement Speciaty Formulatted Corrugating Adhesive
1561	PT027469	N-3332.EM	CN	03 Feb 2010	201080006466.2			ENCAPSULANT FOR INKJET PRINT HEAD
1562	PT027469	N-3332.EM	EP	03 Feb 2010	10739055.1			ENCAPSULANT FOR INKJET PRINT HEAD
1563	PT027469	N-3332.EM	JP	03 Feb 2010	2011-548417			ENCAPSULANT FOR INKJET PRINT HEAD
1564	PT027469	N-3332.EM	KR	03 Feb 2010	2011-7019526			ENCAPSULANT FOR INKJET PRINT HEAD
1565	PT027469	N-3332.EM	TW	21 Jan 2010	99101654			ENCAPSULANT FOR INKJET PRINT HEAD
1566	PT027518	N-3339.ADH	AU	11 Jun 2010	201060018			THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS
1567	PT027518	N-3339.ADH	BR	11 Jun 2010	PI1010733-9			THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS
1568	PT027518	N-3339.ADH	CL	11 Jun 2010	2011-3114			THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS
1569	PT027518	N-3339.ADH	CN	11 Jun 2010	201080025530.1			THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS
1570	PT027518	N-3339.ADH	EP	11 Jun 2010	10786894.5			THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS
1571	PT027518	N-3339.ADH	IN	11 Jun 2010	2457/MUMNP/2011			THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS
1572	PT027518	N-3339.ADH	JP	11 Jun 2010	2012-515173			THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS
1573	PT027518	N-3339.ADH	KR	11 Jun 2010	10-2011-7029574			THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS

	A	B	D	E	F	G	H	M
1574	PT027518	N-3339.ADH	RU	11 Jun 2010	2011154144			THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS
1575	PT027518	N-3339.ADH	US	12 Dec 2011	13/323090			THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS
1576	PT027733	N-3341.PSA	BR	06 Sep 2012	BR112012022560-0			CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES
1577	PT027733	N-3341.PSA	CN	09 Mar 2011	201180012600.4			CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES
1578	PT027733	N-3341.PSA	EP	09 Mar 2011	11753966.8			CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES
1579	PT027733	N-3341.PSA	JP					CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES
1580	PT027733	N-3341.PSA	KR	09 Mar 2011	2012-7026328			CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES
1581	PT027733	N-3341.PSA	US	07 Sep 2012	13/606066			CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES
1582	PT027582	N-3342.NWN	BR	19 Aug 2010	PCT/US2010/45954			Low Temperature Hot Melt Adhesives for Disposable Articles
1583	PT027582	N-3342.NWN	CA	19 Aug 2010	2770457			Low Temperature Hot Melt Adhesives for Disposable Articles
1584	PT027582	N-3342.NWN	CN	20 Feb 2012	201080036909.2			Low Temperature Hot Melt Adhesives for Disposable Articles
1585	PT027582	N-3342.NWN	EP	19 Aug 2010	10810577.6			Low Temperature Hot Melt Adhesives for Disposable Articles
1586	PT027582	N-3342.NWN	JP	19 Aug 2010	2012-525678			Low Temperature Hot Melt Adhesives for Disposable Articles
1587	PT027582	N-3342.NWN	KR	19 Aug 2010	2012-7007172			Low Temperature Hot Melt Adhesives for Disposable Articles

	A	B	D	E	F	G	H	M
1588	PT027582	N-3342.NWN	US	20 Feb 2012	13/400218			Low Temperature Hot Melt Adhesives for Disposable Articles
1589	PT027577	N-3343.PKG	BR	30 Jul 2010	BR112012002264.4			Low Application Temperature Hot Melt Adhesive
1590	PT027577	N-3343.PKG	CN	31 Jan 2012	201080034001.8			Low Application Temperature Hot Melt Adhesive
1591	PT027577	N-3343.PKG	EP	30 Jul 2010	10805084.0			Low Application Temperature Hot Melt Adhesive
1592	PT027577	N-3343.PKG	JP	30 Jan 2012	2012-523064			Low Application Temperature Hot Melt Adhesive
1593	PT027577	N-3343.PKG	KR	28 Feb 2012	2012-7005227			Low Application Temperature Hot Melt Adhesive
1594	PT027577	N-3343.PKG	US	30 Jan 2012	13/361197			Low Application Temperature Hot Melt Adhesive
1595	PT027572	N-3346.ADH	BR	18 Nov 2009	PI0921170-5			Moisture-Curable Hot-Melt Adhesive
1596	PT027572	N-3346.ADH	CN	18 Nov 2009	200980152897.7			Moisture-Curable Hot-Melt Adhesive
1597	PT027572	N-3346.ADH	JP	27 Nov 2008	2008-302038			Moisture-Curable Hot-Melt Adhesive
1598	PT027572	N-3346.ADH	US	26 May 2011	13/116573	04 Dec 2012	8324299	Moisture-Curable Hot-Melt Adhesive
1599	PT027599	N-3347.PKG	US	20 Jun 2012	13/528441			On-Guard System
1600	PT027920	N-3348.NWN	BR	17 Feb 2012	PCT/US2012/25609			Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles
1601	PT027920	N-3348.NWN	CA	17 Feb 2012	PCT/US2012/25609			Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles
1602	PT027920	N-3348.NWN	CN	17 Feb 2012	PCT/US2012/25609			Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles
1603	PT027920	N-3348.NWN	EP	17 Feb 2012	12747804.8			Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles
1604	PT027920	N-3348.NWN	IN	17 Feb 2012	PCT/US2012/25609			Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles
1605	PT027920	N-3348.NWN	JP	17 Feb 2012	PCT/US2012/25609			Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles
1606	PT027920	N-3348.NWN	KR	17 Feb 2012	PCT/US2012/25609			Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles
1607	PT027920	N-3348.NWN	MX	17 Feb 2012	PCT/US2012/25609			Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles

	A	B	D	E	F	G	H	M
1608	PT027920	N-3348.NWN	RU	17 Feb 2012	PCT/US2012/25609			Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles
1609	PT027920	N-3348.NWN	US	14 Mar 2013	13/833811			Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles
1610	PT027667	N-3349.BDG	US	01 Dec 2010	12/957842			Moisture Curable Adhesives
1611	PT027684	N-3350.BKB	CN	20 Dec 2010	201080062237.2			Moisture Cure Hot Melt Adhesives
1612	PT027684	N-3350.BKB	EP	20 Dec 2010	10843509.0			Moisture Cure Hot Melt Adhesives
1613	PT027684	N-3350.BKB	US	22 Jun 2012	13/530565			Moisture Cure Hot Melt Adhesives
1614	PT027777	N-3352.ADH	BR	15 Apr 2011	BR112012027110-5			Silicone-Acrylic Copolymer
1615	PT027777	N-3352.ADH	CN	15 Apr 2011	201180030690.X			Silicone-Acrylic Copolymer
1616	PT027777	N-3352.ADH	EP	15 Apr 2011	11772467.4			Silicone-Acrylic Copolymer
1617	PT027777	N-3352.ADH	IN	15 Apr 2011	PCT/US2011/32609			Silicone-Acrylic Copolymer
1618	PT027777	N-3352.ADH	JP	15 Apr 2011	PCT/US2011/32609			Silicone-Acrylic Copolymer
1619	PT027777	N-3352.ADH	KR	15 Apr 2011	PCT/US2011/32609			Silicone-Acrylic Copolymer
1620	PT027777	N-3352.ADH	RU	15 Apr 2011	2012149840			Silicone-Acrylic Copolymer
1621	PT027777	N-3352.ADH	US	14 Sep 2012	13/617968			Silicone-Acrylic Copolymer
1622	PT027812	N-3354.EM	CN	28 Jul 2011	201180039855.X			Radiation Curable Temporary Adhesive for Use in High Temperature Applications
1623	PT027812	N-3354.EM	EP	28 Jul 2011	11818534.7			Radiation Curable Temporary Adhesive for Use in High Temperature Applications
1624	PT027812	N-3354.EM	JP	28 Jul 2011	2013-524861			Radiation Curable Temporary Adhesive for Use in High Temperature Applications
1625	PT027812	N-3354.EM	KR	15 Feb 2013	10-2013-7003816			Radiation Curable Temporary Adhesive for Use in High Temperature Applications
1626	PT027812	N-3354.EM	TW	16 Aug 2011	100129276			Radiation Curable Temporary Adhesive for Use in High Temperature Applications
1627	PT027812	N-3354.EM	US	14 Sep 2012	13/618203			Radiation Curable Temporary Adhesive for Use in High Temperature Applications
1628	PT027817	N-3355.CRG	CA	29 Jul 2011	2747524			Corrugating Adhesive and Use Thereof
1629	PT027817	N-3355.CRG	US	26 Jul 2011	13/190825			Corrugating Adhesive and Use Thereof

	A	B	D	E	F	G	H	M
1630	PT027818	N-3356.NWN	BR	24 Aug 2011	PCT/US11/48933			Low Application Temperature Amorphous Poly-a-olefin Adhesive
1631	PT027818	N-3356.NWN	CA	24 Aug 2011	2807966			Low Application Temperature Amorphous Poly-a-olefin Adhesive
1632	PT027818	N-3356.NWN	CN	24 Aug 2011	201180041300.9			Low Application Temperature Amorphous Poly-a-olefin Adhesive
1633	PT027818	N-3356.NWN	EP	24 Aug 2011	11820578.0			Low Application Temperature Amorphous Poly-a-olefin Adhesive
1634	PT027818	N-3356.NWN	IN	24 Aug 2011	PCT/US11/48933			Low Application Temperature Amorphous Poly-a-olefin Adhesive
1635	PT027818	N-3356.NWN	JP	24 Aug 2011	2013-526124			Low Application Temperature Amorphous Poly-a-olefin Adhesive
1636	PT027818	N-3356.NWN	KR	24 Aug 2011	PCT/US11/48933			Low Application Temperature Amorphous Poly-a-olefin Adhesive
1637	PT027818	N-3356.NWN	MX	24 Aug 2011	MX/a/2013/002214			Low Application Temperature Amorphous Poly-a-olefin Adhesive
1638	PT027818	N-3356.NWN	RU	24 Aug 2011	2013113169			Low Application Temperature Amorphous Poly-a-olefin Adhesive
1639	PT027818	N-3356.NWN	US	20 Feb 2013	13/771439			Low Application Temperature Amorphous Poly-a-olefin Adhesive
1640	PT027833	N-3357.CRG	BR	09 Sep 2011				Improved Adhesive Having Insulative Properties
1641	PT027833	N-3357.CRG	CN	08 Mar 2013	201180043368.0			Improved Adhesive Having Insulative Properties
1642	PT027833	N-3357.CRG	EP	09 Sep 2011	11824167.8			Improved Adhesive Having Insulative Properties
1643	PT027833	N-3357.CRG	JP	09 Sep 2011	2013-528321			Improved Adhesive Having Insulative Properties
1644	PT027833	N-3357.CRG	KR	09 Sep 2011	2013-7009093			Improved Adhesive Having Insulative Properties
1645	PT027833	N-3357.CRG	MX	09 Sep 2011	MX/a/2013/002701			Improved Adhesive Having Insulative Properties
1646	PT027833	N-3357.CRG	US	25 Feb 2013	13/775348			Improved Adhesive Having Insulative Properties
1647	PT027853	N-3358.PKG	BR					Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation
1648	PT027853	N-3358.PKG	CN					Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation

	A	B	D	E	F	G	H	M
1649	PT027853	N-3358.PKG	EP	21 Nov 2011	11842029.8			Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation
1650	PT027853	N-3358.PKG	JP					Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation
1651	PT027853	N-3358.PKG	KR					Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation
1652	PT027853	N-3358.PKG	RU					Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation
1653	PT027853	N-3358.PKG	US	05 Mar 2013	13/785296			Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation
1654	PT027916	N-3360.EM	CN					Self-Aligned Graphene Polymer Nanocomposites
1655	PT027916	N-3360.EM	EP					Self-Aligned Graphene Polymer Nanocomposites
1656	PT027916	N-3360.EM	JP					Self-Aligned Graphene Polymer Nanocomposites
1657	PT027916	N-3360.EM	KR					Self-Aligned Graphene Polymer Nanocomposites
1658	PT027916	N-3360.EM	TW	24 Feb 2012	101106344			Self-Aligned Graphene Polymer Nanocomposites
1659	~~PT027916~~	~~N-3360.EM~~	~~US~~	~~14 Mar 2013~~	~~13/803282~~			~~Self-Aligned Graphene Polymer Nanocomposites~~
1660	PT027918	N-3361.PKG	WO	04 Apr 2012	PCT/US2012/032063			Hot Melt Adhesives For Multilayer Structure Enclosures
1661	PT027921	N-3363.NWN	BR					Stretch Film Lamination Adhesive
1662	PT027921	N-3363.NWN	CA					Stretch Film Lamination Adhesive
1663	PT027921	N-3363.NWN	CN					Stretch Film Lamination Adhesive

	A	B	D	E	F	G	H	M
1664	PT027921	N-3363.NWN	EP					Stretch Film Lamination Adhesive
1665	PT027921	N-3363.NWN	IN					Stretch Film Lamination Adhesive
1666	PT027921	N-3363.NWN	JP					Stretch Film Lamination Adhesive
1667	PT027921	N-3363.NWN	KR					Stretch Film Lamination Adhesive
1668	PT027921	N-3363.NWN	MX					Stretch Film Lamination Adhesive
1669	PT027921	N-3363.NWN	RU					Stretch Film Lamination Adhesive
1670	PT027921	N-3363.NWN	US	15 Mar 2013	13/832917			Stretch Film Lamination Adhesive
1671	PT031069	N-3364.EM	TW	06 Jun 2013	102120189			Vinyl Carbosiloxane Resins
1672	PT031069	N-3364.EM	WO	06 Jun 2012	PCT/CN2012/076509			Vinyl Carbosiloxane Resins
1673	PT028001	N-3365.ADH	TW	27 Aug 2012	101131052			Lenticular Print Three Dimensional Image Display Device and Method of Fabricing the Same
1674	PT028001	N-3365.ADH	WO	27 Jul 2012	PCT/US2012/48541			Lenticular Print Three Dimensional Image Display Device and Method of Fabricing the Same
1675	PT028002	N-3366.EM	US	14 Sep 2012	13/618392			Curable Oxetane Ester Compositions
1676	PT028016	N-3367.ADH	TW	27 Aug 2012	101131051			Lenticular Print Three Dimensional Image Display and Device of Fabricing the Same
1677	PT028016	N-3367.ADH	WO	27 Jul 2012	PCT/US2012/48595			Lenticular Print Three Dimensional Image Display and Device of Fabricing the Same
1678	PT019333	N-3368.EM (ID-11-076)	TW	26 Mar 2012	101110427			Electroless Plating of Silver onto Graphite
1679	PT031207	N-3370.ADH	WO	23 Jan 2013	PCT/US2013/22714			UV Curable Metallic Decorative Compositions

	A	B	D	E	F	G	H	M
1680	~~PT027276~~	~~N-7991~~	~~US~~	~~07 Jun 1995~~	~~08/480982~~	~~01 Oct 1996~~	~~5561204~~	~~SPHERICAL CURING AGENT FOR EPOXY RESIN, CURING~~ AGENT MASTERBATCH FOR EPOXY RESINAND THEIR PREPARATION
1681	~~PT027276~~	~~N-7991~~	~~US~~	~~07 Jun 1995~~	~~08/480983~~	~~22 Oct 1996~~	~~5567792~~	~~SPHERICAL CURING AGENT FOR EPOXY RESIN, CURING~~ AGENT MASTERBATCH FOR EPOXY RESINAND THEIR PREPARATION
1682	~~PT027276~~	~~N-7991~~	~~US~~	~~07 Jun 1995~~	~~08/472617~~	~~10 Sep 1996~~	~~5554714~~	~~SPHERICAL CURING AGENT FOR EPOXY RESIN, CURING~~ AGENT MASTERBATCH FOR EPOXY RESINAND THEIR PREPARATION
1683	~~PT027276~~	~~N-7991~~	~~US~~	~~07 Jun 1995~~	~~08/472616~~	~~07 Jan 1997~~	~~5591814~~	~~SPHERICAL CURING AGENT FOR EPOXY RESIN, CURING~~ AGENT MASTERBATCH FOR EPOXY RESINAND THEIR PREPARATION
1684	~~PT027276~~	~~N-7991~~	~~US~~	~~07 Jun 1995~~	~~08/478067~~	~~20 Aug 1996~~	~~5548058~~	~~SPHERICAL CURING AGENT FOR EPOXY RESIN, CURING~~ AGENT MASTERBATCH FOR EPOXY RESINAND THEIR PREPARATION
1685	PT027282	N-8324	EP	14 Jun 1994	94921329.2	04 Sep 2002	0707524	SOLDERABLE COMPOSITION EXHIBITING ELECTRICAL ANISOTROPY☐
1686	PT027298	N-AAA1230-1	US	16 Oct 2006	11/581759	12 Jan 2010	7645637	Methods for Attaching Tin Semiconductor Die
1687	~~PT027363~~	~~N-CRODA-2~~	~~US~~	~~23 Mar 1994~~	~~08/216799~~	~~28 Feb 1995~~	~~5392592~~	~~HOT MELT PRESSURE SENSITIVE ADHESIVE PACKAGING,~~ PREFORM AND METHOD
1688	PT027434	N-JM28397	US	22 Dec 1995	08/577256	05 Jan 1999	5855821	MATERIALS FOR SEMICONDUCTOR DEVICE ASSEMBLIES
1689	PT027436	N-JM28716	US	10 Jun 1996	08/664200	21 Jul 1998	5783621	METHOD OF DECREASING BLEED FROM ORGANIC-BASED FORMULATIONS AND ANTI-BLEEDCOMPOSITIONS☐
1690	PT027437	N-JM29822	US	06 Jun 1997	08/868508	28 Apr 1998	5744533	
1691	PT027438	N-JM29849	US	11 Feb 1997	08/798864	12 Jan 1999	5859105	ORGANOSILICON-CONTAINING COMPOSITIONS CAPABLE OF RAPID CURING AT LOW TEMPERATURE
1692	PT027439	N-JM30414	US	11 Feb 1997	08/798863	22 Dec 1998	5852092	ORGANOSILICON-CONTAINING COMPOSITIONS HAVING ENHANCED ADHESIVE PROPERTIES

	A	B	D	E	F	G	H	M
1693	PT027440	N-JM30677	US	19 May 1997	08/859792	15 Jun 1999	5912316	
1694	PT027441	N-JM31088	US	23 Sep 1997	08/935575	12 Jan 1999	5859110	METHOD OF DECREASING BLEED FROM ORGANIC-BASED FORMULATIONS AND ANTI-BLEEDCOMPOSITIONS
1695	PT027442	N-JM31635	US	12 Aug 1998	09/133507	02 May 2000	6057402	
1696	~~PT027443~~	~~N-JM32175~~	~~US~~	~~08 Jul 1994~~	~~08/272354~~	~~02 Jul 1996~~	~~5532513~~	
1697	~~PT027443~~	~~N-JM32175~~	~~US~~	~~01 Jul 1998~~	~~09/108923~~			
1698	PT019217	PT019217	WO	25 Jul 2012	PCT/US2012/48131			High Polymer Content Hot Melt Adhesives For Disposable Articles
1699	PT028003	PT019284	US	24 Aug 2011	13/216563			Starch-Based Adhesive Compositions and Use Thereof
1700	PT019562	PT019562	TW	29 Apr 2013	102115304			Thermally Insulative Composition And Electronic Devices Assembled Therewith
1701	PT019562	PT019562	WO	05 Apr 2013	PCT/US2013/35424			Thermally Insulative Composition And Electronic Devices Assembled Therewith
1702	PT031248		AR	17 May 2013	P130101711			Thermoplastic film for packaging olefin hot melt adhesives
1703	PT031327		AR	24 May 2013	P130101811			Process and methods for preparing flow-able pellets of olefin adhesives with low crystaalinity
1704	PT031387		CA					2 Component Fluid Metering and Mixing
1705	PT019096		CN	20 Jul 2011	201110203015.4			AgBN based adhesive for capacitors
1706	PT031387		CN					2 Component Fluid Metering and Mixing

	A	B	D	E	F	G	H	M
1707	PT031387		DE					2 Component Fluid Metering and Mixing
1708	PT031445		GB	14 Mar 2013	GB1304624.8			Hybrid adhesives capable of bonding low surface energy substrates
1709	PT019109		TW	14 Jun 2012	101121266			Shape memory polymer backgrinding film
1710	PT019096		TW	04 Jul 2012	101123990			AgBN based adhesive for capacitors
1711	PT031535		TW	28 Sep 2012	101136021			Curable Oxetane Ester Compositions
1712	PT031252		TW	03 Apr 2013	102112225			FILM FOR FILLING THROUGH THE HOLE INTERCONNECTS AND POST PROCESSING FOR INTERCONNECTS SUBSTRATES
1713	PT031397		TW	4/29/2013	102115307			Curable Encapsulants And Use Thereof
1714	PT031248		TW	16 May 2013	102117432			Thermoplastic film for packaging olefin hot melt adhesives
1715	PT031327		TW	5/24/2013	102118481			Process and methods for preparing flow-able pellets of olefin adhesives with low crystaalinity
1716	PT019456		TW	17 Jul 2013	102125632			Silver sintering die-attach paste with fluxing agent for metal adhesion
1717	PT031231		TW	18 Jul 2013				Reactive Hot Melt Adhesives
1718	PT031365		US	14 Sep 2012	13/617440			Non Reactive Hot Melt Adhesive Compositions with Wide Service Temperature Range
1719	~~PT031649~~		~~US~~	~~26 Oct 2012~~	~~61/718841~~			
1720	~~PT031411~~		~~US~~	~~02 Nov 2012~~	~~61/721756~~			Hot Melt for overmolding applications II
1721	~~PT031394~~		~~US~~	~~16 Nov 2012~~	~~61/727375~~			A Gap Filling Waterborne Adhesive Formulation
1722	~~PT031231~~		~~US~~	~~18 Dec 2012~~	~~61/738644~~			Reactive Hot Melt Adhesives
1723	~~PT031231~~		~~US~~	~~18 Dec 2012~~	~~61/738586~~			Reactive Hot Melt Adhesives

	A	B	D	E	F	G	H	M
1724	PT031323		US	10 Jan 2013	13/738348			Preparation of Polymers Terminated with Alkoxysilane Groups
1725	~~PT031771~~		~~US~~	~~28 Jan 2013~~	~~61/757353~~			
1726	~~PT031367~~		~~US~~	~~21 Feb 2013~~	~~61/767447~~			Hot Melt adhesives based on Polypropylene (co) polymers and use thereof
1727	PT031519		US	12 Mar 2013	13/795403			Use of APAO Polymers for End of Line Packaging applications
1728	PT031778		US	12 Mar 2013	13/795228			Hot Melt adhesive Compositions Based on Ethylene Vinyl Acetate Copolymer
1729	PT031248		US	13 Mar 2013	13/800445			Thermoplastic film for packaging olefin hot melt adhesives
1730	PT019456		US	14 Mar 2013	13/827117			Silver sintering die-attach paste with fluxing agent for metal adhesion
1731	PT031327		US	14 Mar 2013	13/803814			Process and methods for preparing flow-able pellets of olefin adhesives with low crystaalinity
1732	PT031394		US	14 Mar 2013	13/804230			A Gap Filling Waterborne Adhesive Formulation
1733	PT031411		US	14 Mar 2013	13/804811			Hot Melt for overmolding applications II
1734	PT031606		US	14 Mar 2013	13/826451			A heat activated waterborne adhesive formulation containig microspheres to enable fiber reduction in packaging material
1735	PT019496		US	15 Mar 2013	13/838164			Prepreg Curing Process FOr Preparing Composites Having Superior Surface Finish and High Fiber Consolidation
1736	PT031231		US	15 Mar 2013	13/839138			Reactive Hot Melt Adhesives
1737	PT031387		US	15 Mar 2013	13/840063			2 Component Fluid Metering and Mixing
1738	PT031473		US	15 Mar 2013	13/833425			Prepreg Curing Process For Preparing Composites Having Superior Surface Finish and High Fiber Consolidation

	A	B	D	E	F	G	H	M
1739	PT031555		US	15 Mar 2013	13/839785			Anaerobic Curable Compositions
1740	PT031612		US	15 Mar 2013	13/840171			Thermosetting Resin Compositions With Low Coefficient of Thermal Expansion
1741	PT031617		US	15 Mar 2013	13/840248			Oxetaine-Contanining Compounds and Compositions Thereof
1742	PT031591		US	15 Mar 2013	13/770295			Reactive Hot Melt Adhesives
1743	PT031516		US	16 Mar 2013	13/844890			Electronic Devices Assembled With Heat Absorbing and/or Thermally Insulating Composition
1744	PT031487		US	18 Mar 2013	13/846088			Methods and Apparatus For Controlled Single Electron Transfer Living Radical Polymerization
1745	~~PT031661~~		~~US~~	~~22 Mar 2013~~	~~61/804232~~			
1746	~~PT031661~~		~~US~~	~~22 Mar 2013~~	~~61/804232~~			
1747	PT031252		US	29 Mar 2013	13/827698			FILM FOR FILLING THROUGH THE HOLE INTERCONNECTS AND POST PROCESSING FOR INTERCONNECTS SUBSTRATES
1748	~~PT031632~~		~~US~~	~~08 Apr 2013~~	~~61/809633~~			Dispense Tip Cleaning Apparatus
1749	~~PT031924~~		~~US~~	~~10 May 2013~~	~~61/822037~~			Functional Polyisobutylene-Containing Oligomers and Polymers
1750	~~PT031787~~		~~US~~	~~21 May 2013~~	~~61/825766~~			Flexible Cyanoacrylate Compositions
1751	~~PT031844~~		~~US~~	~~23 May 2013~~	~~61/826573~~			Tri-layer Adhesive for the Encapsulation of Electronic Devices
1752	~~PT031959~~		~~US~~	~~07 Jun 2013~~	~~61/832357~~			Diene/Dienophile Couples and Thermosetting Resin Compositions Having Reworkability
1753	~~PT031949~~		~~US~~	~~21 Jun 2013~~	~~61/837769~~			Polyolefin Pressure Sensitive Hot Melt Adhesive